

Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

Evaluation board circuit diagram
and implementation
<MN63Y1208>

Ver 1.3

2013/10/10

Semiconductor Business Group
Industrial Devices Company
Panasonic Corporation

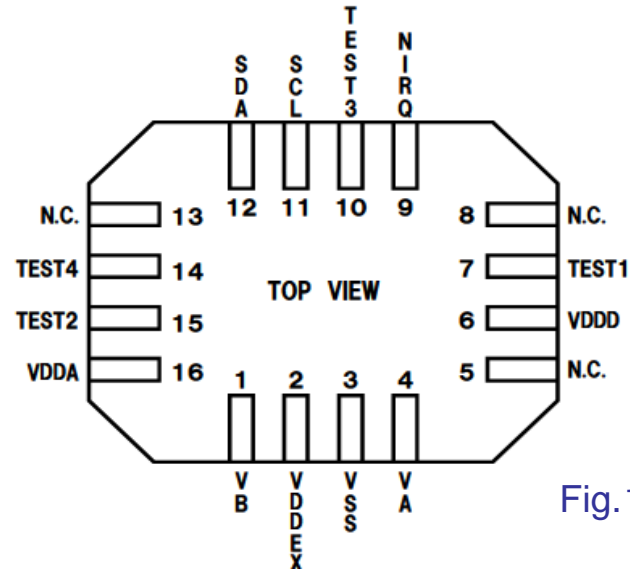


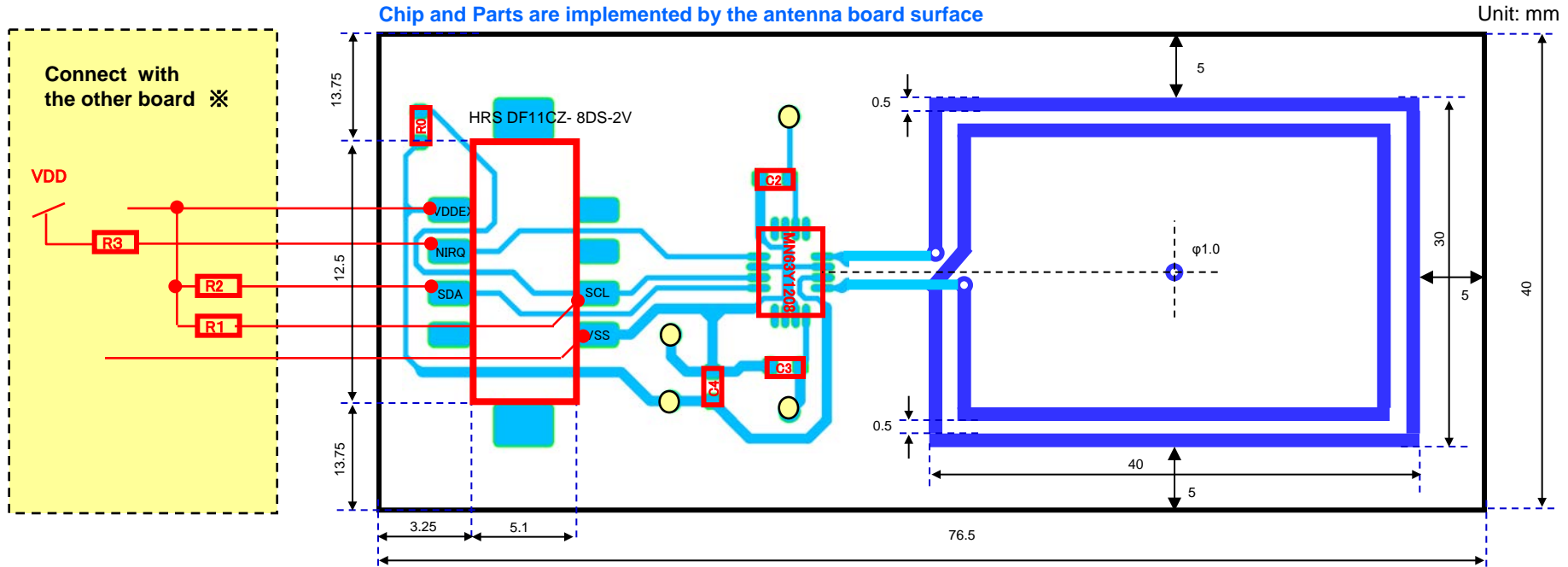
Fig.1 List of pin placement

Tab.1 Pins of the NFC tag

PIN Number	Terminal name	Input/output	Input and output type	function
1	VB	I/O	—	Coil terminal
2	VDDEX	—	Power	Power supply for contact (Input 1.7V ~ 3.6V)
3	VSS	—	GND	Ground
4	VA	I/O	—	Coil terminal
5	N.C.	—	—	Unconnected pin
6	VDDD	—	Power	Digital internal power supply (Connect capacitance between VSS)
7	TEST1	input	—	Test control (Normally connected to VSS)
8	N.C.	—	—	Unconnected pin
9	NIRQ	output	Open Drain	Interrupt request output
10	TEST3	input	—	Test control (Normally connected to VSS)
11	SCL	input	—	HOST I/F (I2C 100kHz)
12	SDA	I/O	Open Drain	HOST I/F (I2C 100kHz)
13	N.C.	—	—	Unconnected pin
14	TEST4	input	—	Test control (Normally connected to VSS)
15	TEST2	input	—	Test control (Normally connected to VSS)
16	VDDA	—	Power	Analog internal power supply (Connect capacitance between VSS)

Figure of pattern of the evaluation board

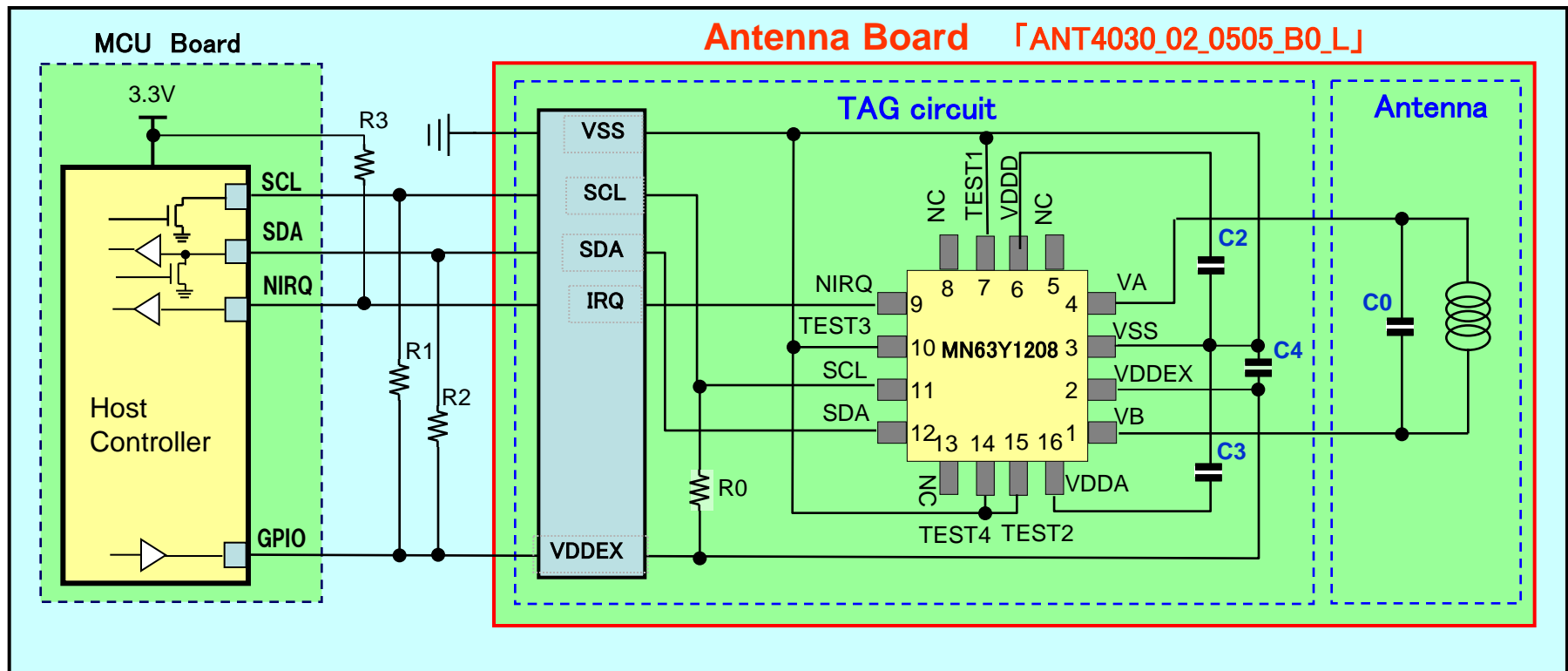
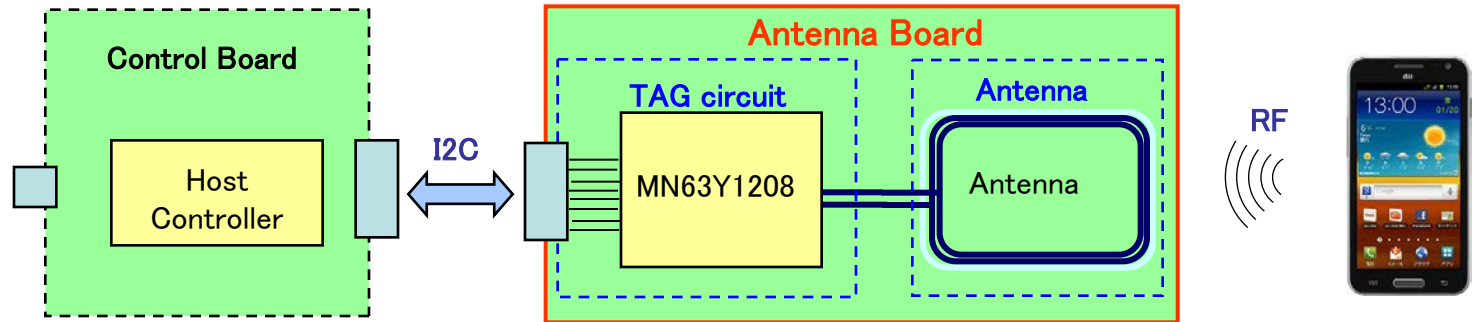
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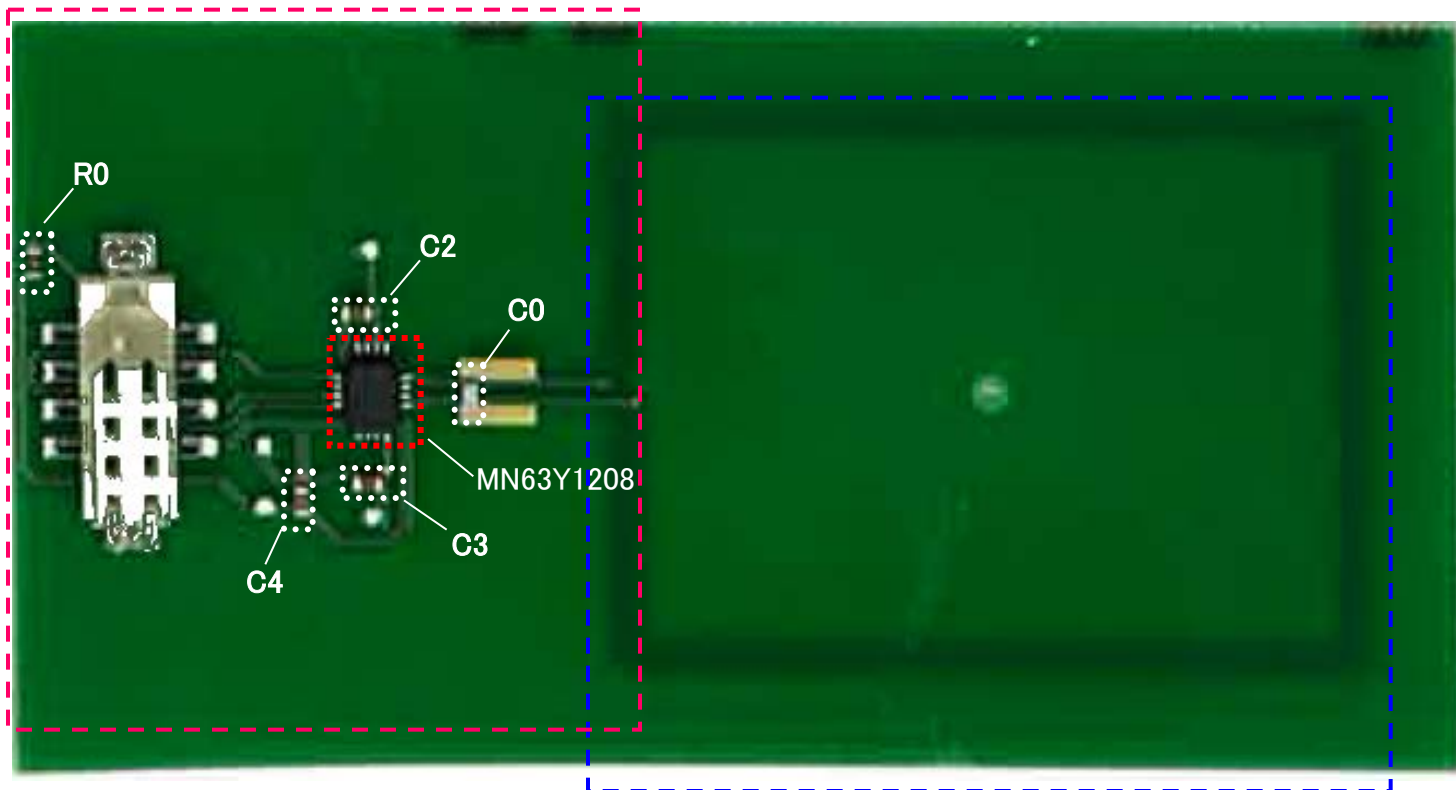
※ Substrate size may differ from the substrate which exists to a visitor.
 ※ I connect pulling up resistance (R,R2,R3) to the microcomputer board of our offer.

External part	Recommendation Value	Detailed explanation
R1,R2	3.3kΩ	It is pulling up resistance for I2C signal lines. Please decide the resistance level in consideration of transmission rate, wiring capacity, current ability. In our NFC tag board "ANT4030_02_0505_B0_L," it is not implemented.
R3	3.3kΩ	It is pulling up resistance for interrupt signal lines. Please decide the resistance level in consideration of wiring capacity, current ability. In our NFC tag board "ANT4030_02_0505_B0_L," it is not implemented.
C2, C3, C4	0.1μF	It is a fixed value at the capacity between the power supply for operation stabilization of the tag LSI. C2 is connected to VDDD, and C3 is connected to VDDA and C4 is connected to VDDEX
R0	100kΩ	It is pulling up resistance to prevent an uncertainty state of SCL causing the malfunction. When NFC tag LSI has the terms of use that R1 is not connected to, I am necessary.

NFC tag system constitution

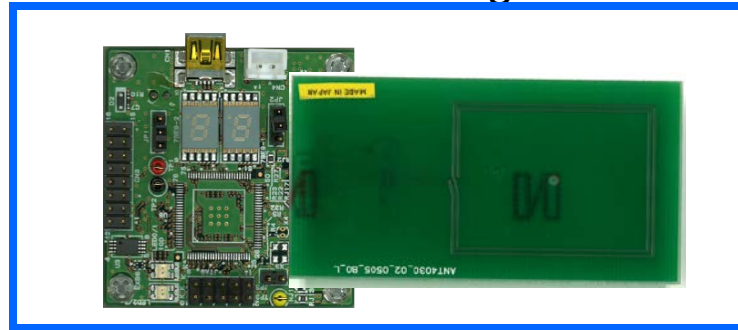


Chip and Parts are implemented by the board surface

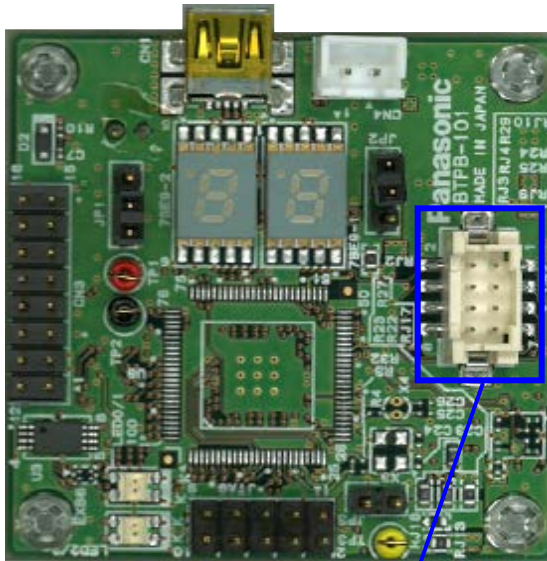


Antenna is implemented by the board back side

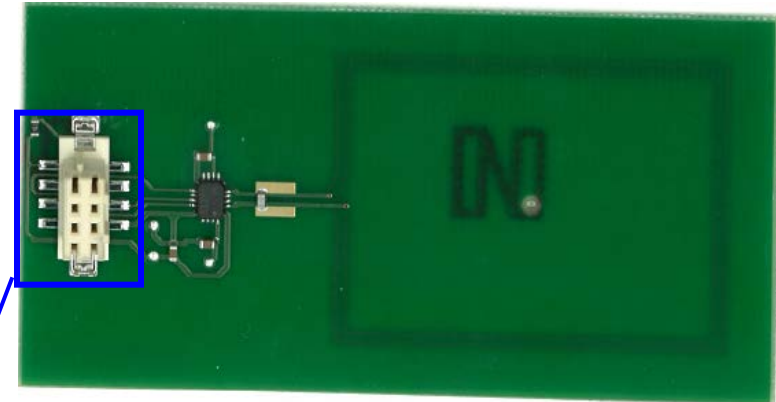
Connection image



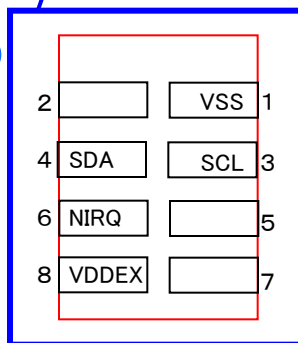
Micon Board [BTPB101-B]



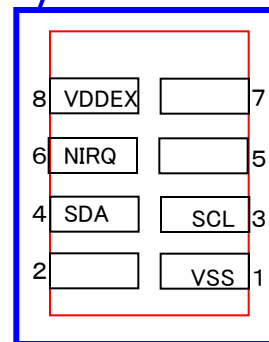
Antenna Board [ANT4030_02_0505_B0_L]



DF11CZ-8DP-2V(27)
(Hirose Electric)



HRS DF11CZ- 8DS-2V
(Hirose Electric)



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